



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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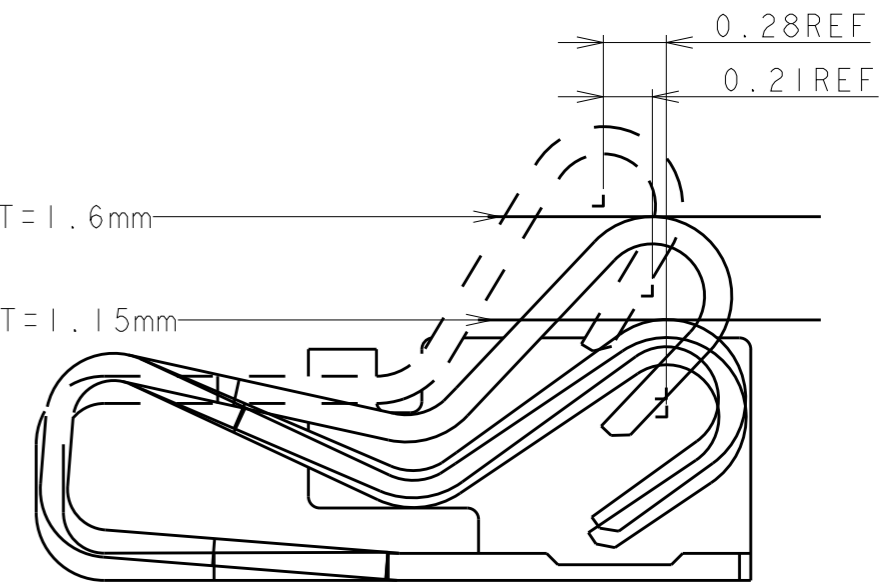
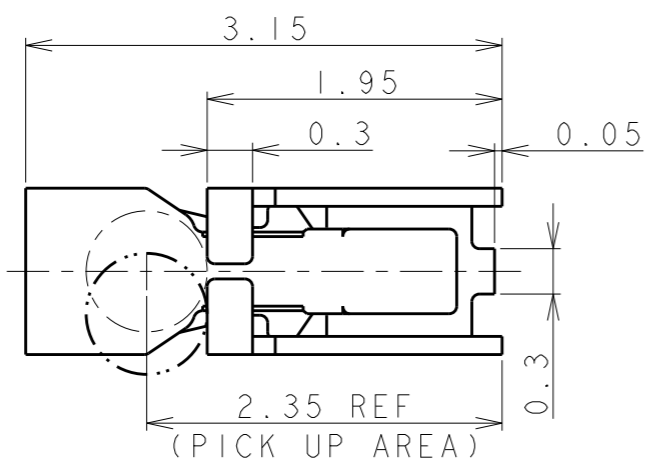
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1

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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
J	-	D1	REVISED	25APR2012	T.Z S.Y
		D2	REVISED FOR ADD *-3, ADD NOTE 7	03JUN2013	R.W S.Y

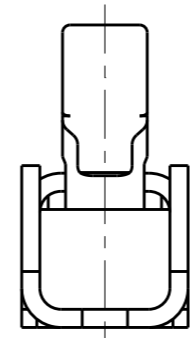
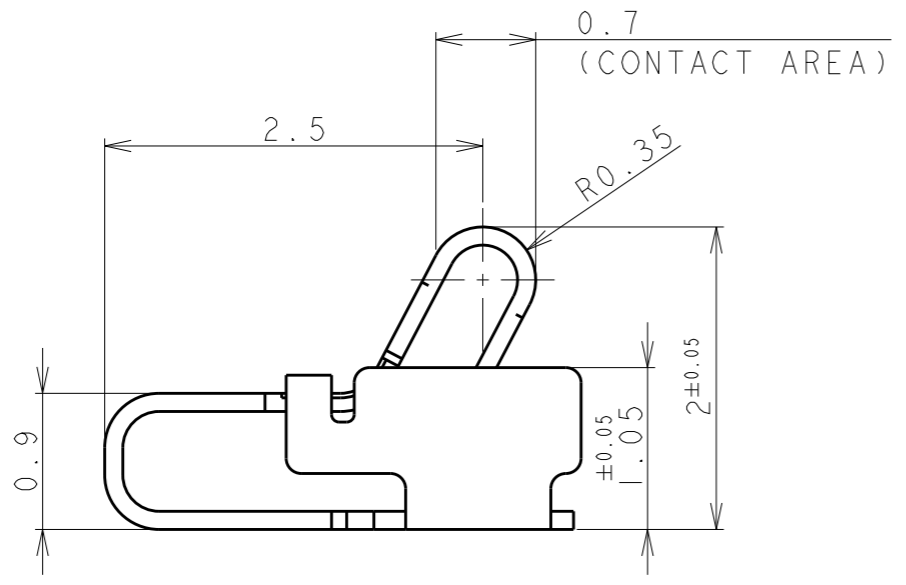
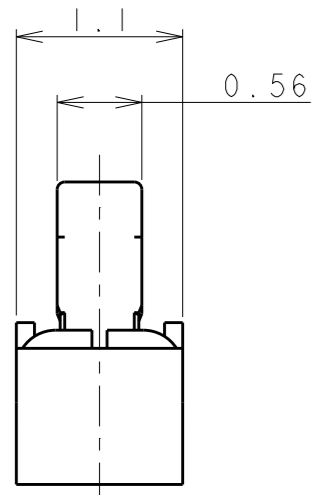
AS SHOWN: -1 & -3



PCB HEIGHT=1.6mm

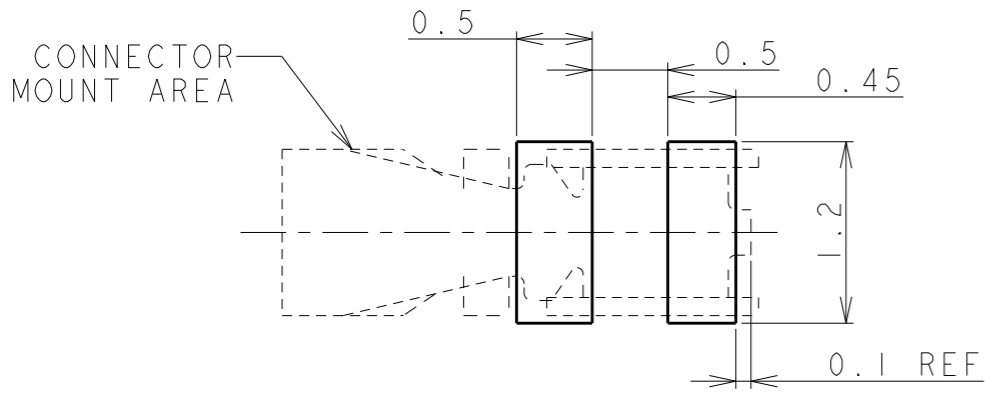
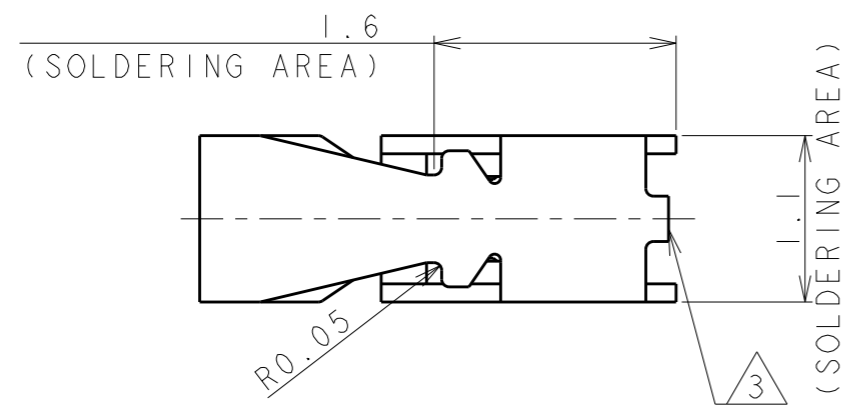
PCB HEIGHT=1.15mm

STROKE CONDITION (REFERENCE)
SCALE 30:1



NOTES:

- △ PRE-PLATING SPECIFICATION:
 Ni UNDER PLATING : 0.8um TO 2.0um
 Au PLATING (CONTACT PLATING) : 0.25um TO 0.5um
 AU PLATING (SOLDER PLATING) : 0.05um TO 0.5um
- △ MATERIAL : COPPER ALLOY, THK.=0.12mm
- △ CUTTING BURR : 0.05mm MAX.
- 4 CIRCUMFERENCE BURRS : 0.03mm MIN.
- 5 DISUSED PACKAGEING MATERIAL : DRYPACK AND BAKING PROCESS.
- △ POST-PLATING SPECIFICATION)
 Ni UNDER PLATING : 0.8um TO 2.0um
 Au PLATING (CONTACT PLATING) : 0.3um MIN.
 AU PLATING (SOLDER PLATING) : 0.01um TO 0.2um
- 7. NORMAL FORCE AT 1.60mm HEIGHT IS 0.3N MIN
 NORMAL FORCE AT 1.15mm HEIGHT IS 1.1N MAX



PCB LAYOUT (REFERENCE)
SCALE 20:1

N/A	△	△	1554901-3
108-78724	△	△	1554901-1
PRODUCT SPEC.	FINISH	MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN Y. KUDO 06NOV2009	TE Connectivity	
DIMENSIONS: mm		CHK C. OHASHI 06NOV2009		
TOLERANCES UNLESS OTHERWISE SPECIFIED: ±0.15		APVD Y. NAKAZAWA 06NOV2009	NAME -	
0 PLC ± 1 PLC ±0.5 2 PLC ±0.13 3 PLC ±0.013 4 PLC ±0.000J ANGLES ±3		PRODUCT SPEC SEE TABLE	SHIELD FINGER 2011	
MATERIAL △2		APPLICATION SPEC -	SIZE A3	CAGE CODE 00779
FINISH △1		WEIGHT 0.0098 g	DRAWING NO C=1554901	RESTRICTED TO -
Customer Drawing		SCALE 20:1	SHEET 1 OF 2	REV D2

4

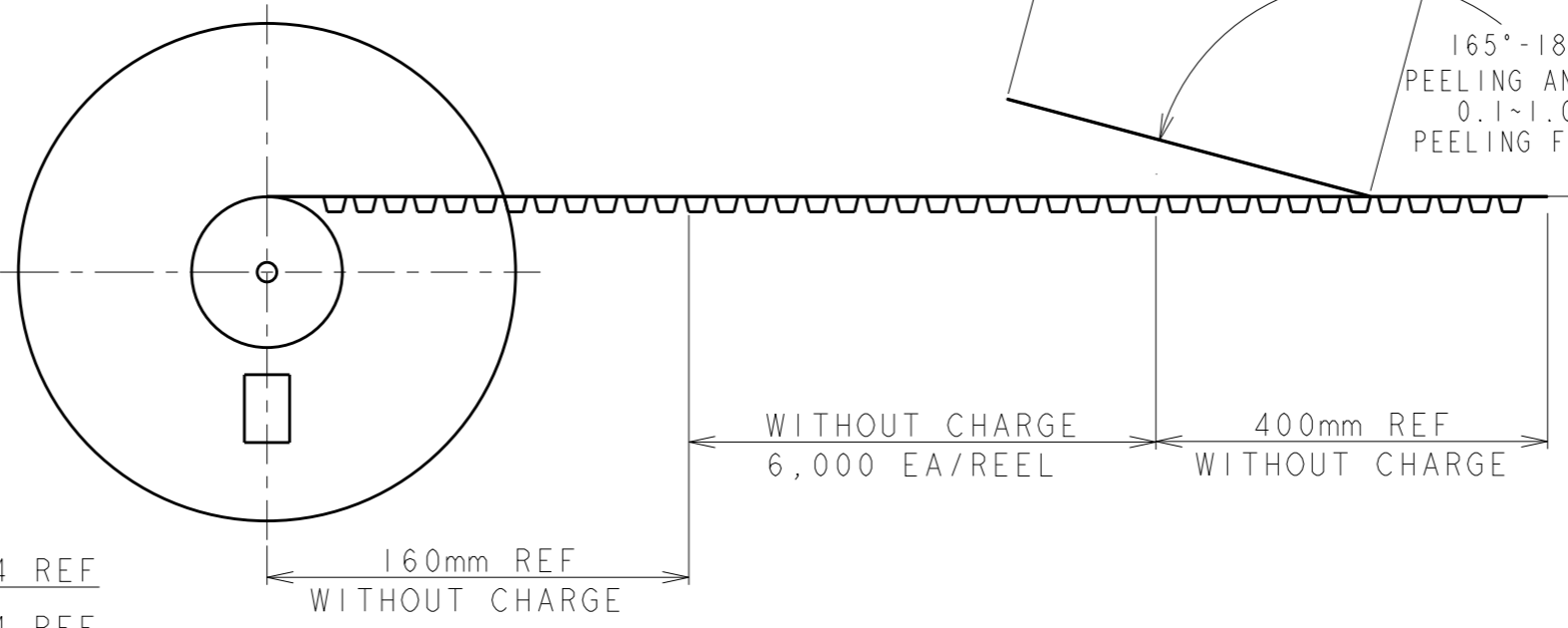
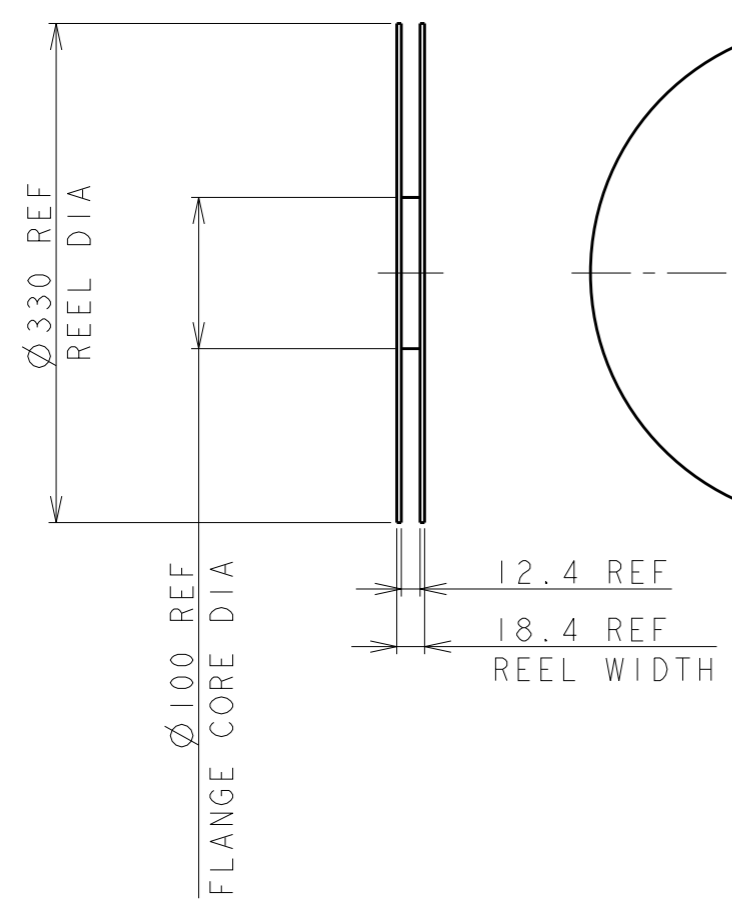
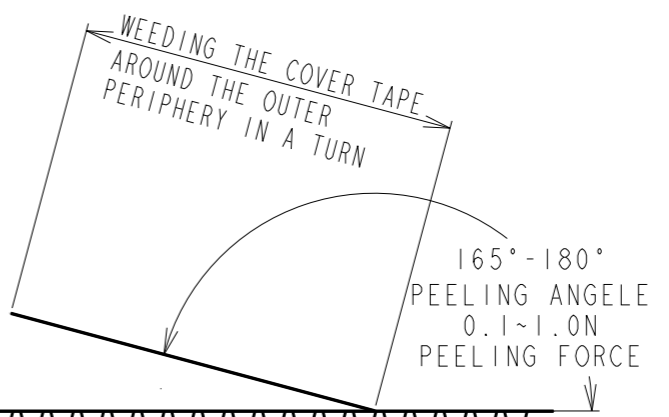
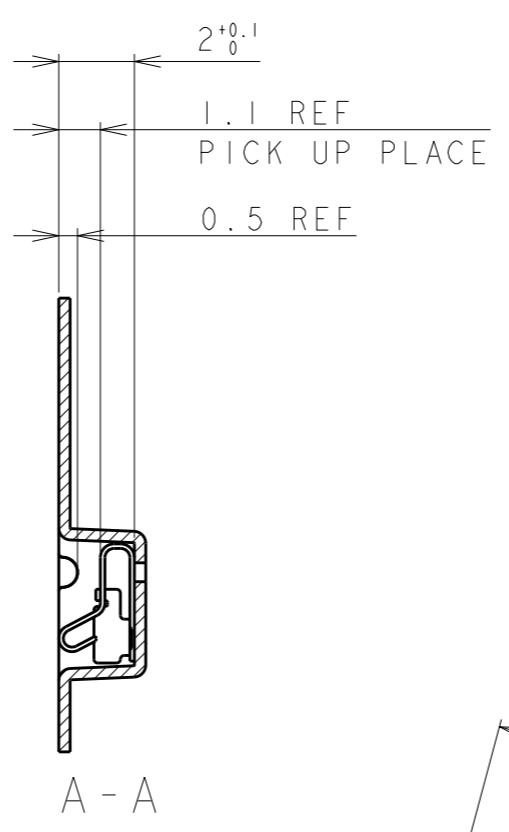
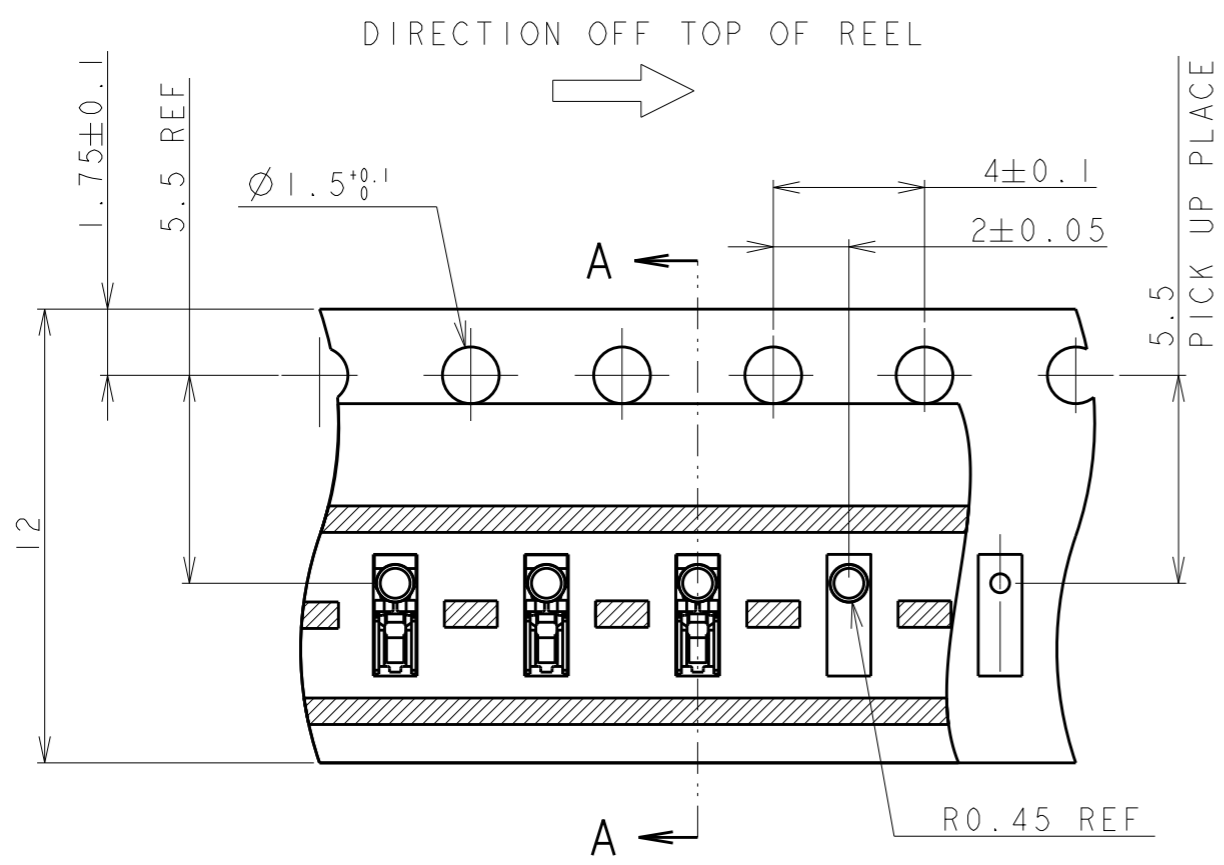
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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
J	-	SEE SHEET 1	-	-	-



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN Y. KUDO 06NOV2009	 TE Connectivity
DIMENSIONS: mm		CHK C. OHASHI 06NOV2009	
TOLERANCES UNLESS OTHERWISE SPECIFIED: ± 0.2		APVD Y. NAKAZAWA 06NOV2009	
0 PLC ± 1 PLC ±0.5 2 PLC ±0.13 3 PLC ±0.013 4 PLC ±0.000J ANGLES ±3		NAME -	
MATERIAL -		PRODUCT SPEC 108-78724	SHIELD FINGER 2011
FINISH -		APPLICATION SPEC -	SIZE -
		WEIGHT 0.0098 g	CAGE CODE A300779
		Customer Drawing	DRAWING NO C-1554901
		SCALE 20:1	RESTRICTED TO -
		SHEET 2 OF 2	REV D2